CLAIMS

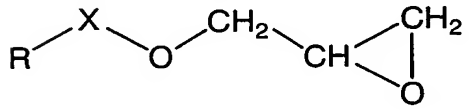
1. A thermosetting resin composition, which comprises the following (A) component and (B) component.

(A) component: at least one kind of phenol resin selected from the group consisting of alkylphenol novolak, a phenol adduct of an aliphatic polymer containing a double bond, and a phenol adduct of an alicyclic polymer containing a double bond

(B) component: epoxy group - containing ethylene copolymer obtained by polymerizing the following ($b_1$) and ($b_2$):

($b_1$) ethylene and/or propylene

($b_2$) monomer represented by the following formula (1):



(1)

(wherein R represents a hydrocarbon group of a carbon number of from 2 to 18 having a double bond, wherein at least one of hydrogen atoms of the hydrocarbon group may be substituted with a halogen atom, a hydroxyl group or a carboxyl group, and X represents a single bond or a carbonyl group.)

2. The thermosetting resin composition according to claim 1, wherein the alkylphenol novolak is a condensate of formalin and phenol substituted with an alkyl group of a carbon number of from 2 to 20.

3. The thermosetting resin composition according to claim 1, wherein a content of a structural unit derived from ($b_2$) is from 1 to 30 parts by weight relative to 100 parts by weight of (B) component.

4. The thermosetting resin composition according to claim 1, wherein the (B) component is a copolymer obtained by polymerizing ($b_1$), ($b_2$) and the following ($b_3$):

($b_3$): a monomer which has a functional group copolymerizable with ethylene, has no functional group reactive with an epoxy group, and is different from either of ($b_1$) and ($b_2$).

5. The thermosetting resin composition according to claim 1, wherein a content of a structural unit derived from ($b_1$) is from 30 to 75 parts by weight relative to 100 parts by weight of the (B) component.

6. The thermosetting resin composition according to claim 1, wherein a weight ratio of the (A) component and the (B) component is (A)/(B)=4/96 to 50/50.

7. The thermosetting resin composition according to claim 1, which further contains (C) component:

(C) component: antioxidant.

8. The thermosetting resin composition according to claim 7, wherein the (C) component is at least one of an antioxidant selected from the group consisting of a phenolic antioxidant, a phosphoric antioxidant and a sulfuric antioxidant.

9. An adhesive, which contains the thermosetting resin composition as defined in claim 1 and the following (D) component:

(D): organic solvent and/or water.

10. The adhesive according to claim 9, wherein a total weight of the (A) component and the (B) component is from 10 to 150 parts by weight relative to 100 parts by weight of the (D) component.

11. An adhesive film, which contains the thermosetting resin composition as defined in claim 1.

12. The adhesive film according to claim 11, which is obtained by coating the adhesive as defined in claim 9 on a support substrate, and drying this.

13. The adhesive film according to claim 11, which is obtained by extrusion molding.

14. An adhesive film, which is obtainable by further irradiating the adhesive film as defined in claim 11 with an electron beam.

15. The adhesive film according to claim 14, which is obtainable by performing electron beam irradiation plural times.

16. A laminate, which is obtainable by laminating the adhesive film as defined in claim 11 or 14 and an adherend, and thermally curing this.